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United States Patent [19]

Antonczak et al.

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[54] **CONFIGURABLE MULTI-PRODUCT ELECTRONICS ENCLOSURE**

[75] Inventors: **Michael J. Antonczak**, Aptos; **Philip G. Yurkonis**, Campbell; **Michael S. Dann**, Mountain View; **Paul S. Montgomery**; **Herbert H. F. Pfeifer**, both of San Francisco; **James G. Ammon**, San Jose, all of Calif.

[73] Assignee: **Sun Microsystems, Inc.**, Mountain View, Calif.

[**] Term: **14 Years**

[21] Appl. No.: **8,431**

[22] Filed: **May 10, 1993**

[52] **U.S. Cl.** **D13/184**

[58] **Field of Search** D13/184; D14/107, D14/101; 361/724, 725, 727, 728, 729

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Primary Examiner—Joel Sincavage
Attorney, Agent, or Firm—Erwin J. Basinski

[57] **CLAIM**

The ornamental design for a configurable multi-product electronics enclosure, as shown and described.

DESCRIPTION

FIG. **1** is a front and upper right perspective view of a configurable multi-product electronics enclosure showing the first embodiment of our new design;

FIG. **2** is a front elevation view of a configurable multi-product electronics enclosure showing the second embodiment our new design. All other plan and elevation views are the same as the first embodiment;

FIG. **3** is a front elevation view of the first embodiment;

FIG. **4** is a front elevation view of a configurable multi-product electronics enclosure showing the third embodiment our new design. All other plan and elevation views are the same as the first embodiment;

FIG. **5** is a is a right side elevation view of the first embodiment, the left side being a mirror image;

FIG. **6** is a is a rear elevation view of the first embodiment;

FIG. **7** is a rear elevation view of a configurable multi-product electronics enclosure showing the fourth embodiment our new design. All other plan and elevation views are the same as the first embodiment;

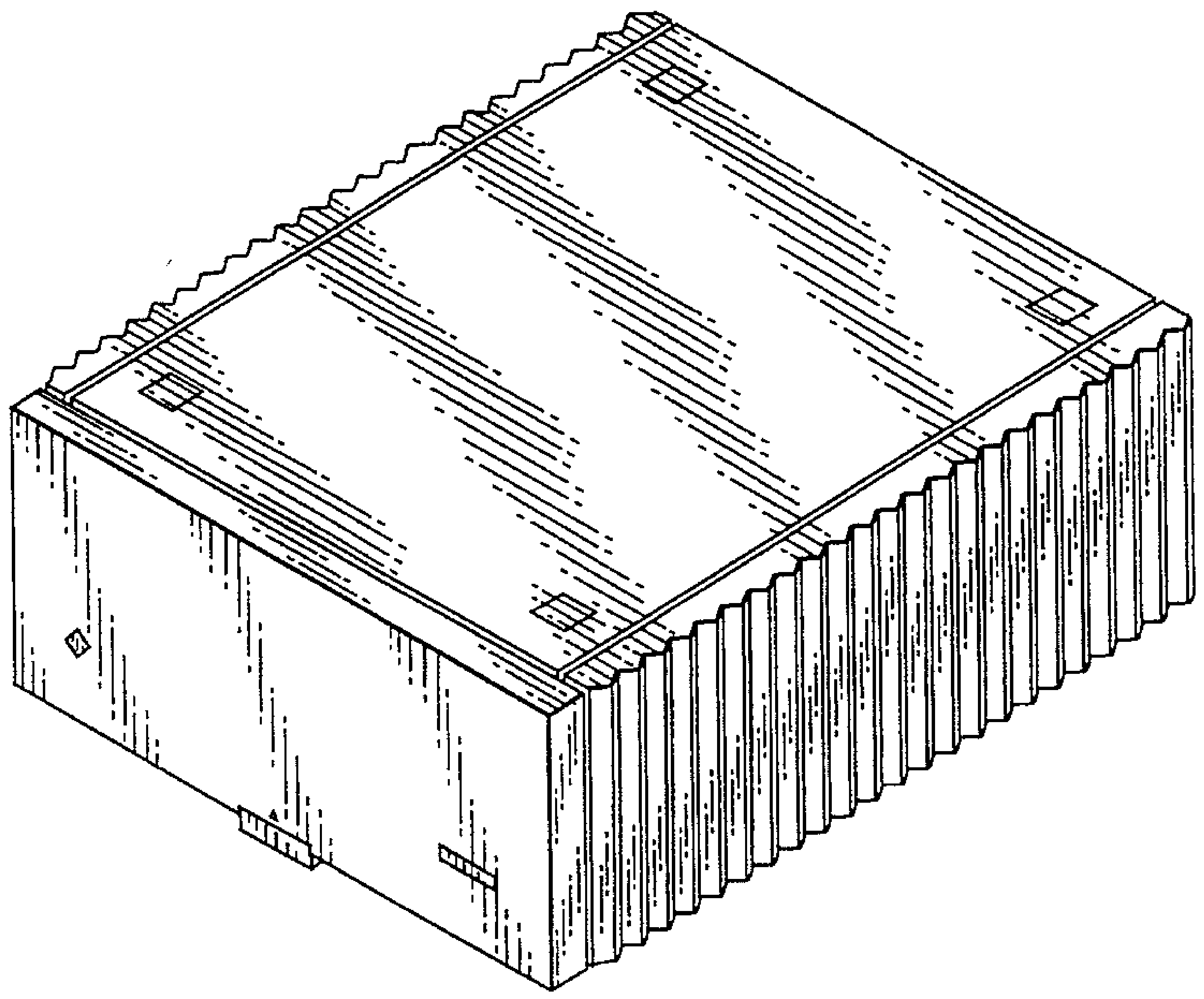
FIG. **8** is a top plan view of the first embodiment;

FIG. **9** is a bottom plan view of the first embodiment;

FIG. **10** is a rear and upper left perspective view of the first embodiment; and,

FIG. **11** is a rear and upper left perspective view of the fourth embodiment.

1 Claim, 8 Drawing Sheets



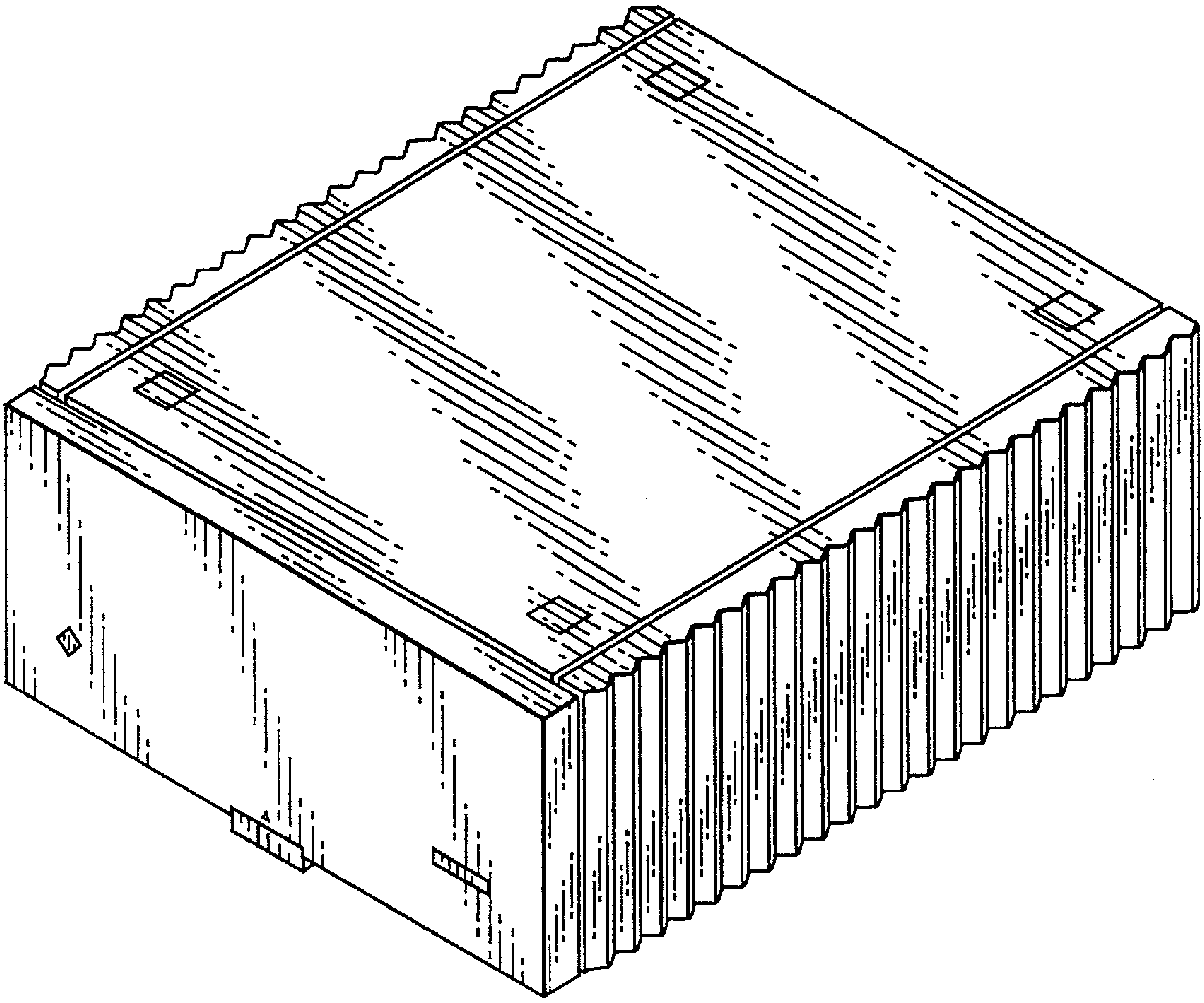


FIG_1

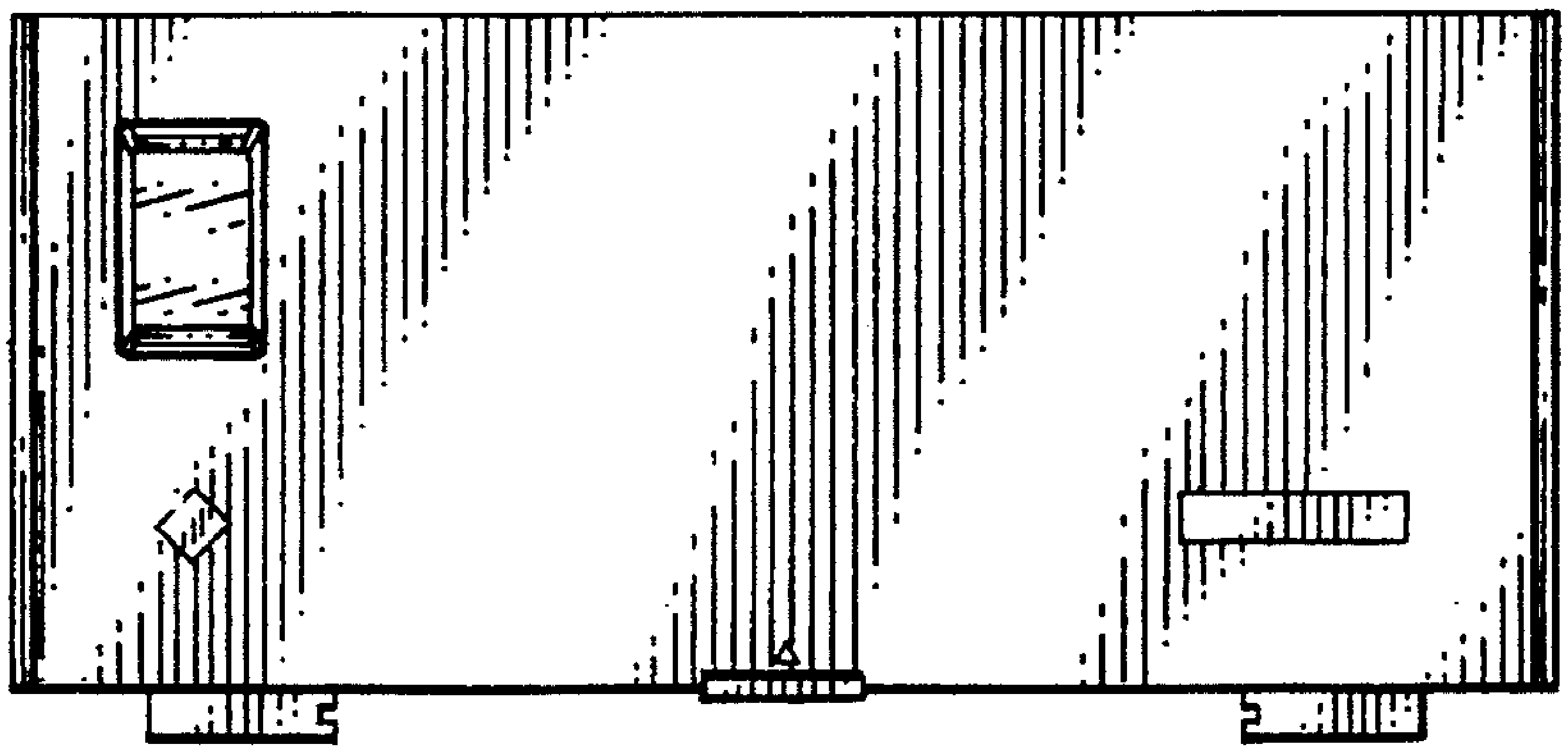


FIG_2

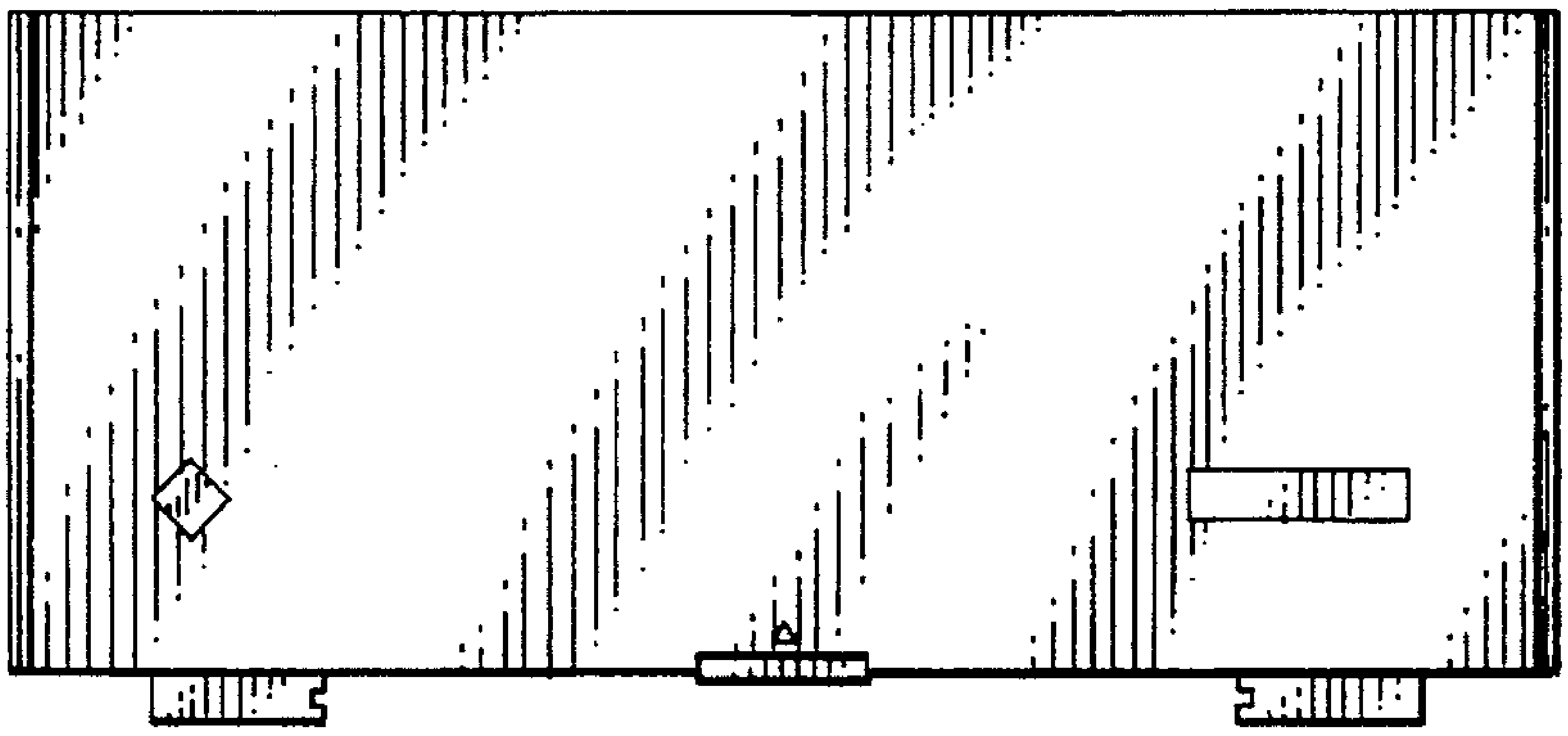


FIG_3

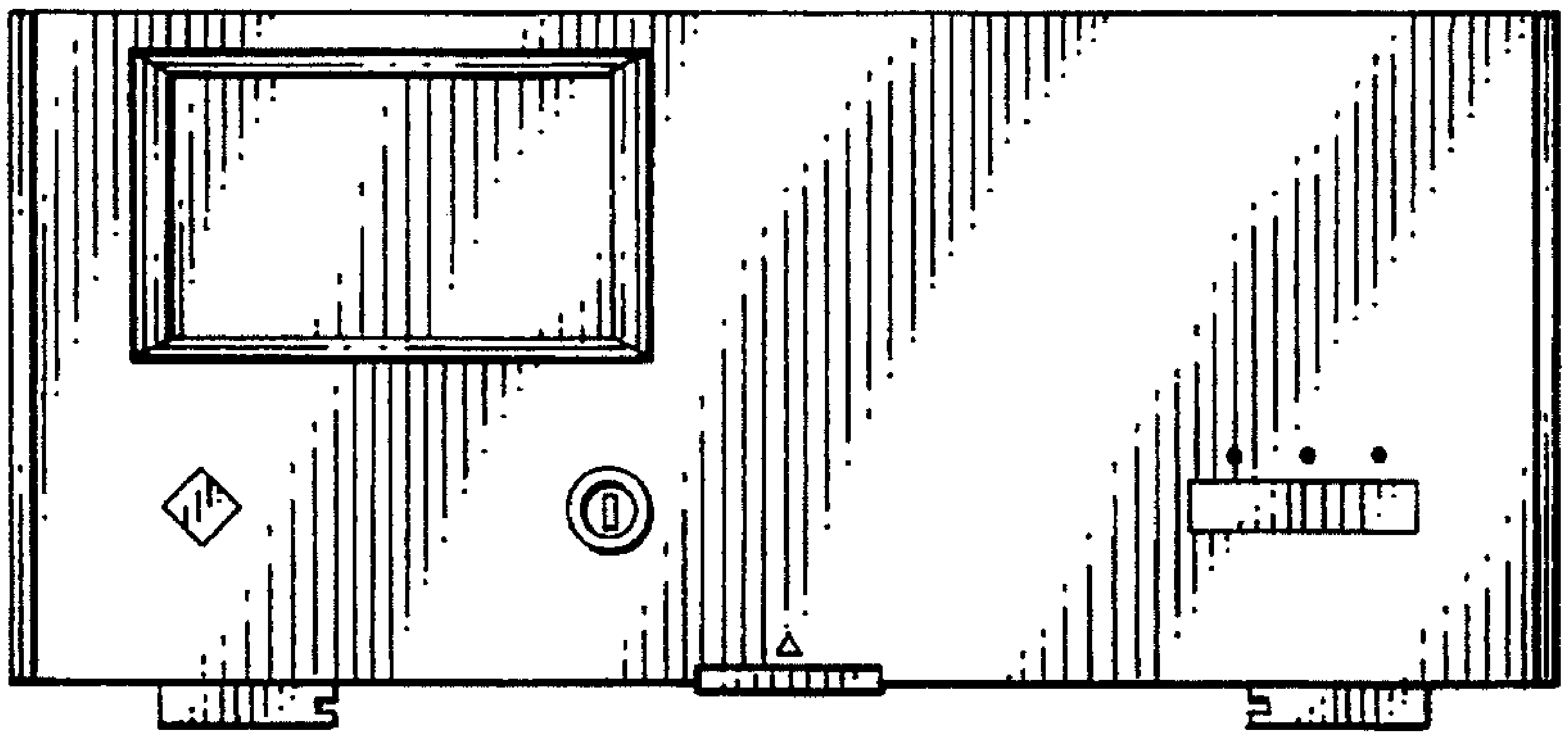


FIG_4

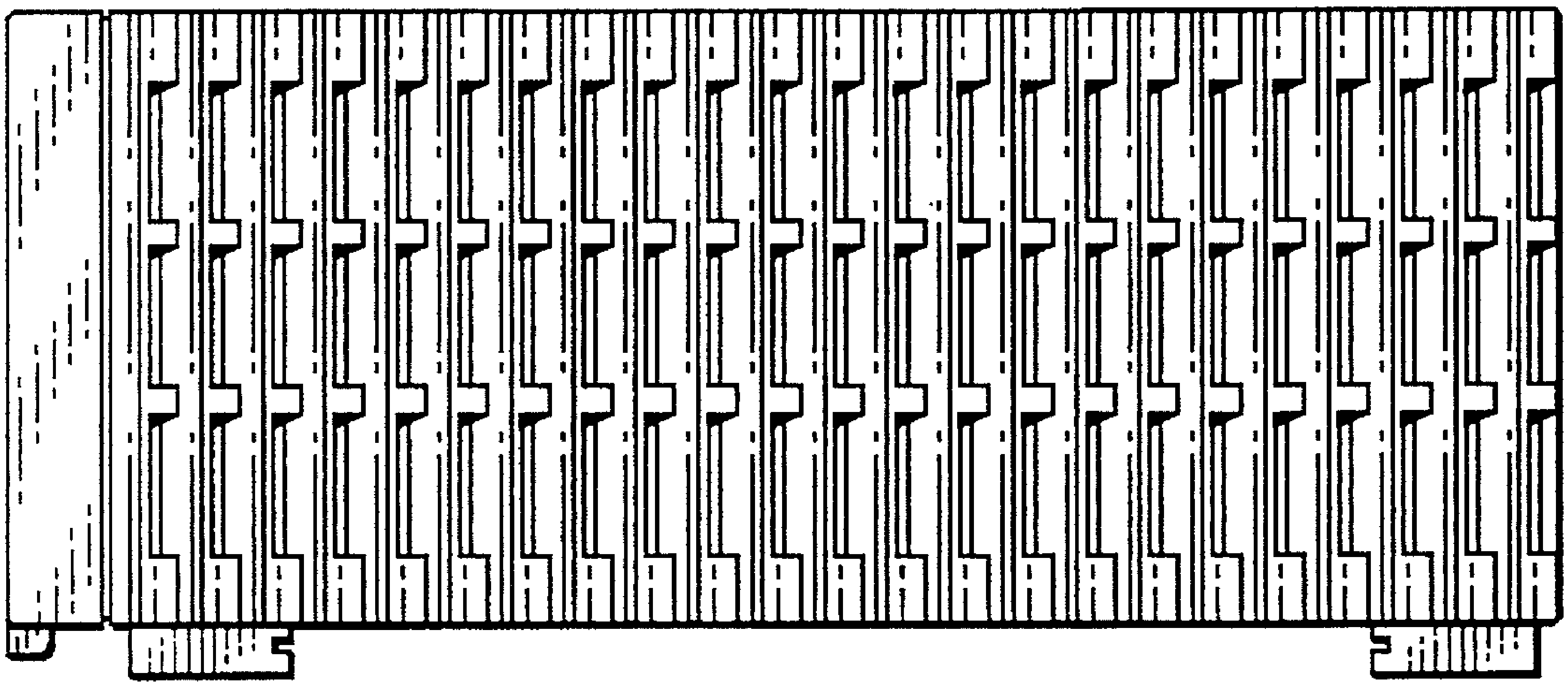


FIG_5

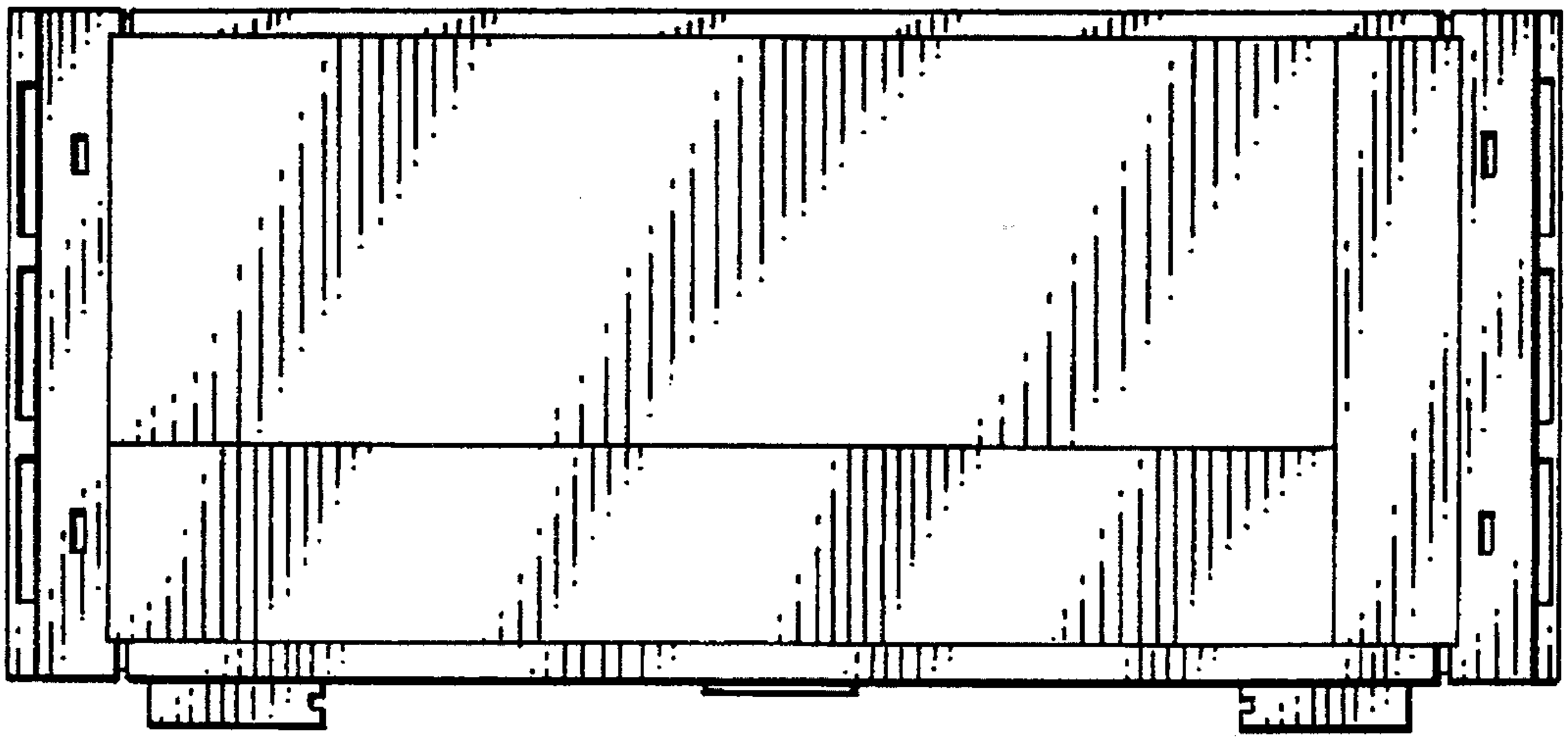


FIG_6

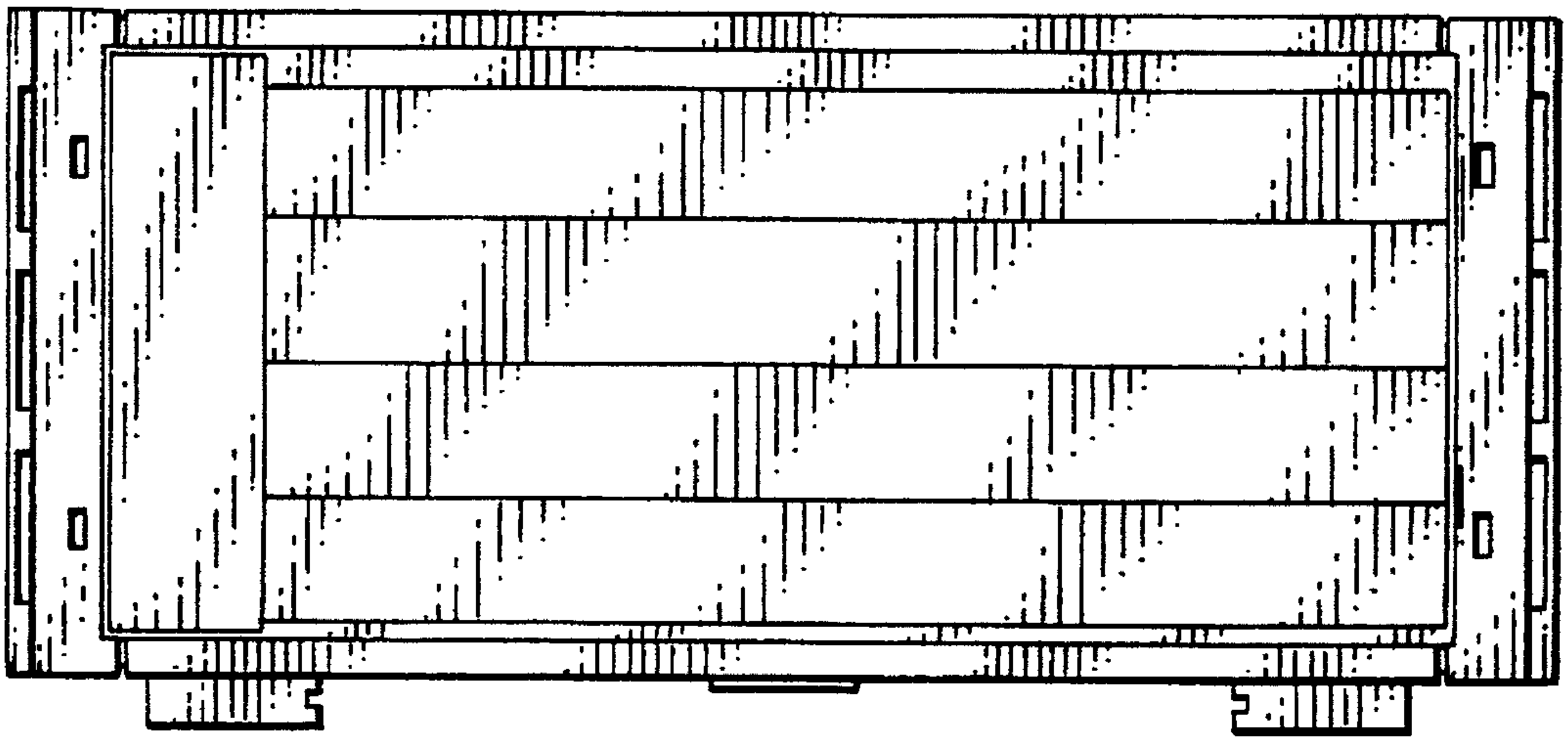


FIG_7

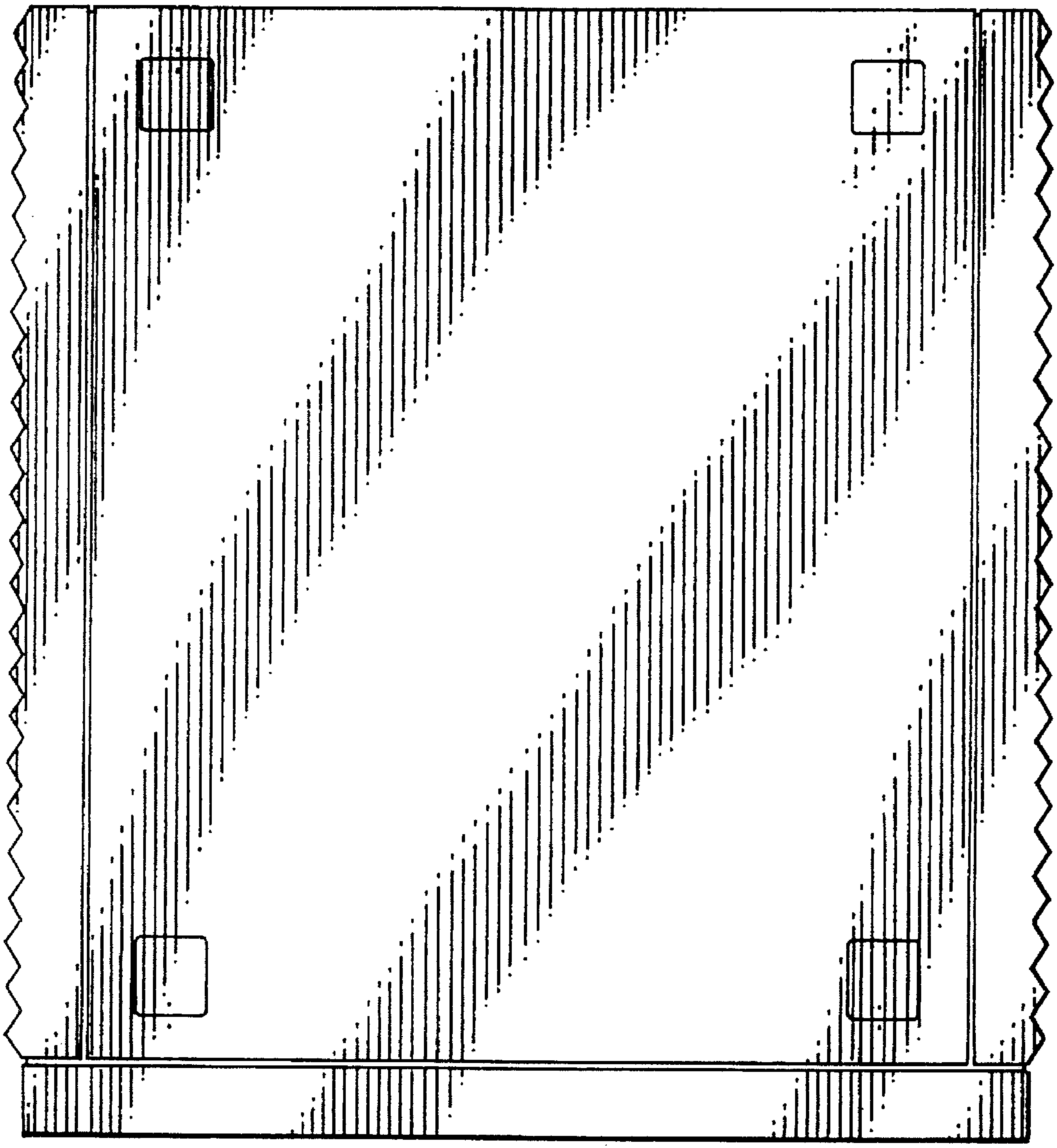


FIG_8

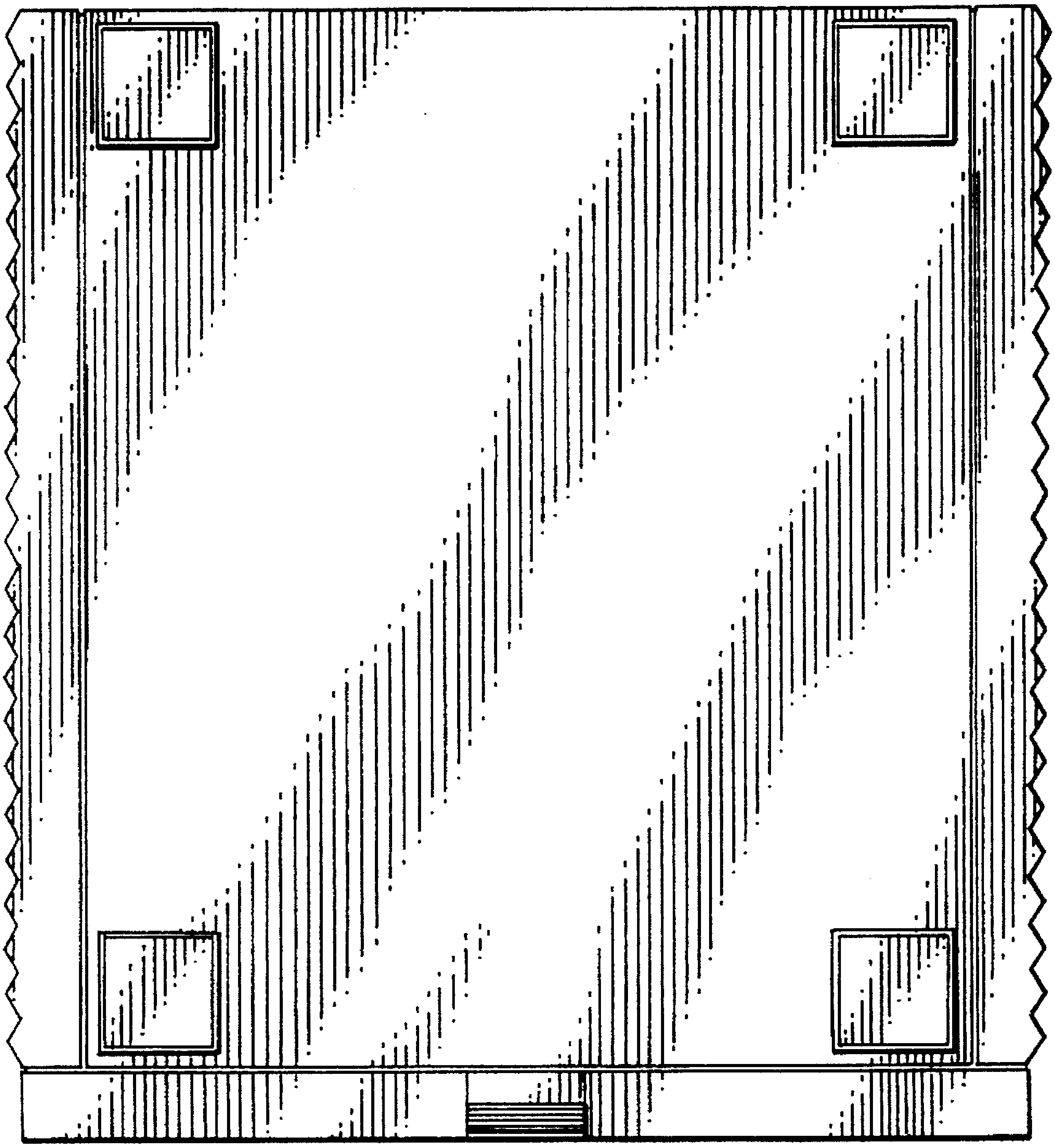


FIG_9

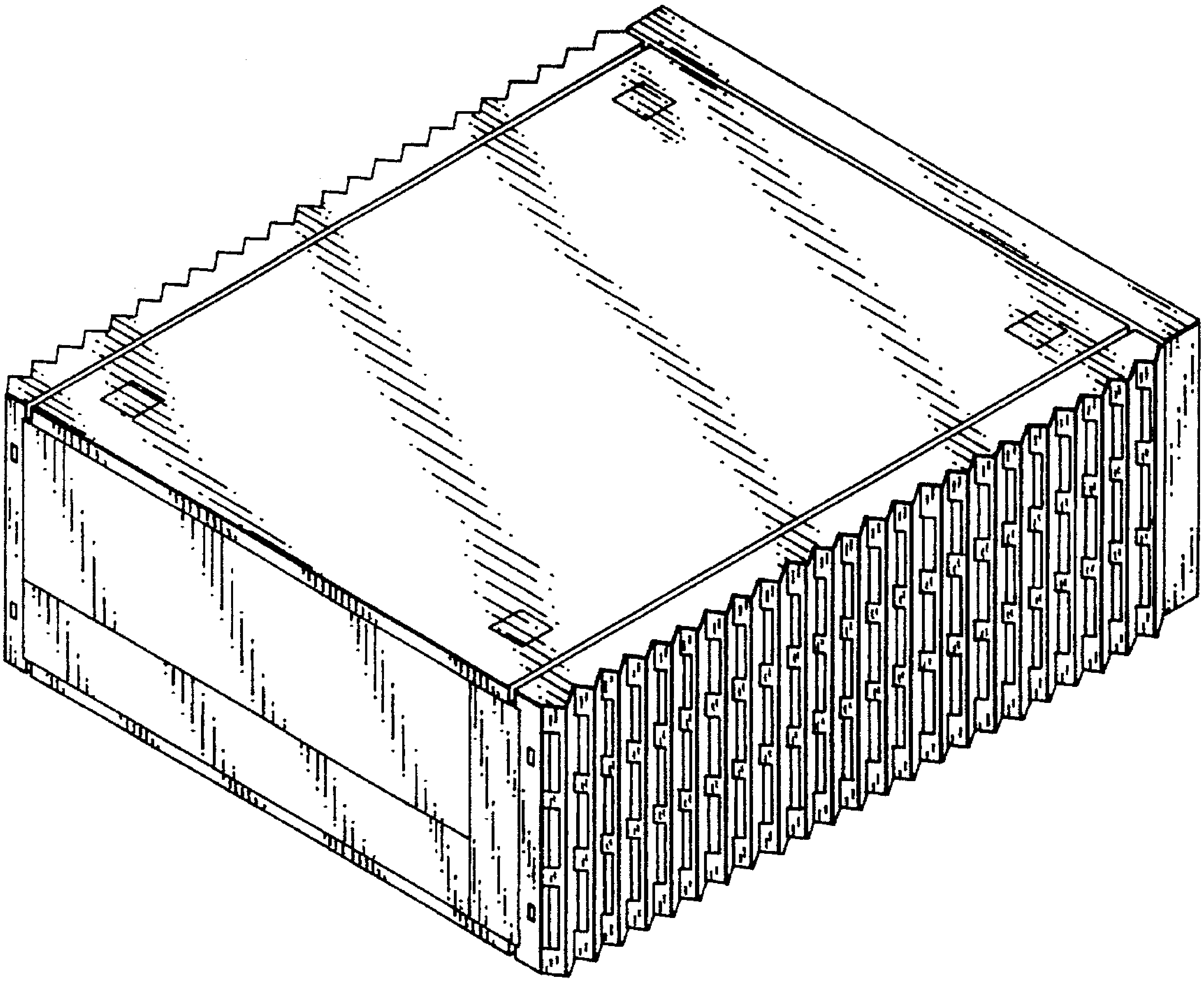


FIG_10

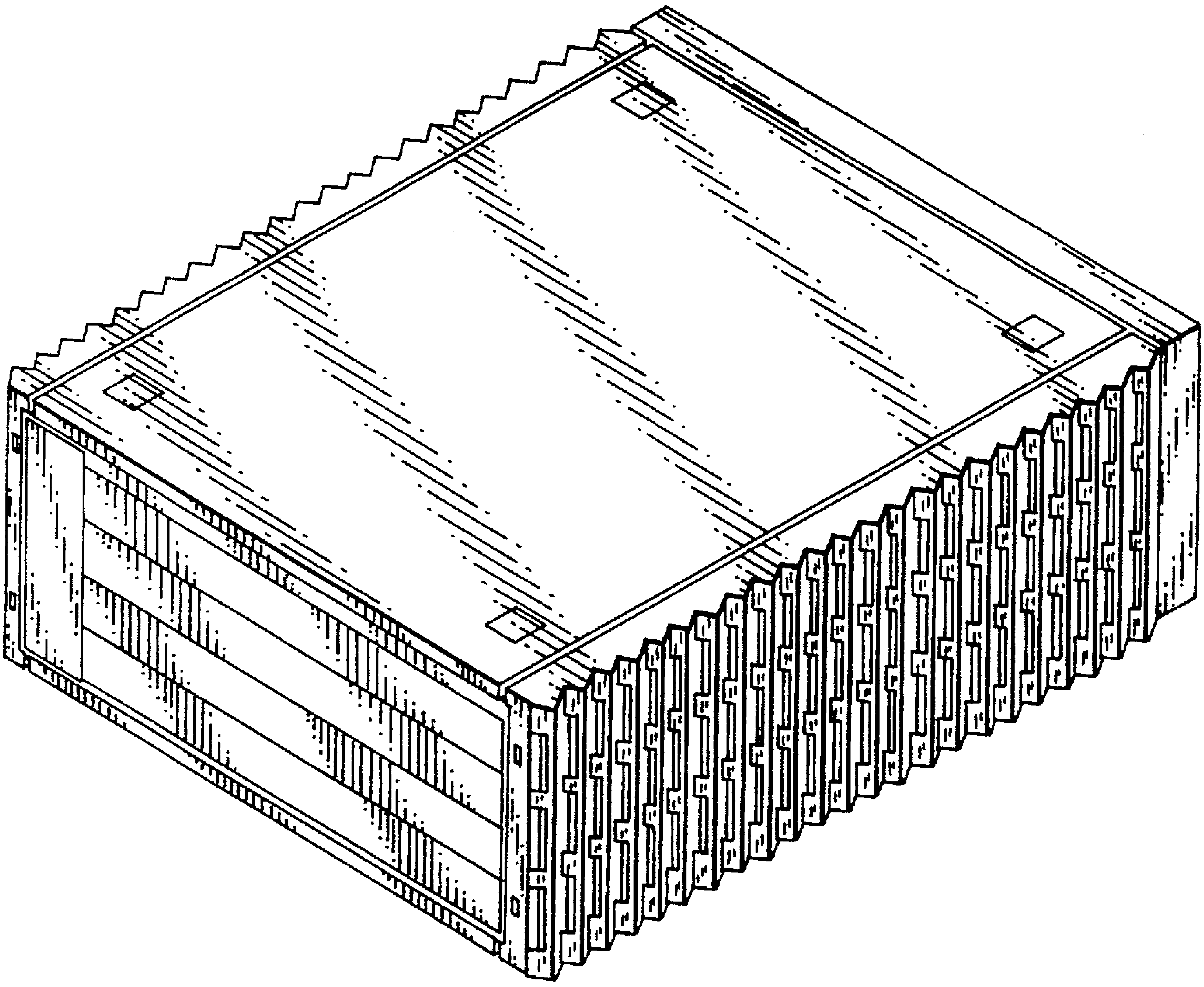


FIG_11